Nidec
All for dreams

RSH-S230TFS (In-tray Model)

新一代IC封装电路板翘曲检测装置
IC Substrate Warpage Inspection System

- 特征 -

1. 新机种
- Achieved the best performance by the renewal optics for advanced inspection.

2. 高生产效率
- Implement the HIGH throughput to further increase productivity.

3. 尺寸紧凑，便于操作
- Compact size with simple structure and improved accessibility/ maintenance.

可支持新一代IC封装电路板3D翘曲检测等
Capable of implementing next-generation IC Substrate 3D warpage inspection.

支持JEDEC Tray
- JEDEC Tray Standard with Flipping Mechanism

支持6个下料分类槽
- Maximum 6 Output Bins

高速度・高精度检测
- High Throughput & Accuracy

优化用户界面
- Optimized Interface, Increased Usability

Key Specifications	Optical Sensor RSH-23i
2D sensor method	2D CMOS Area Camera & LED Lighting (dark & bright field)
3D sensor method	3D Laser Triangulation
Typical warpage range (μm)	≤350μm
Typical device size (width) x (Depth) (mm)	7mm (W) x 7mm (D) - 120mm (W) x 120mm (D)
Typical substrate thickness Range (mm)	0.2mm - 4mm
2D resolution(X,Y) (μm)	5.5μm
3D resolution(X,Y) (μm)	X: 10μm Y:Programmable 1-50μm
3D resolution(Z) (μm) on flat surface	0.22μm
FOV (mm)	>22.5mm
2D accuracy mean bias (μm)※	±2.6μm
3D accuracy mean bias (μm)※	±1.7μm
Repeatability bump height (μm)※	3σ mean ≦ 2um
Repeatability bump diameter (μm)※	3σ mean ≦ 3um
Repeatability warpage (μm)※	3σ mean ≦ 2um
Machine size/weight	Size: 1860mm (W) x 2400mm (D) x 2050mm (H) ※Protrusion part is not included. Weight: approx. 3000kg

※: Specifications are subject to change. Performance specifications on golden units. Exact specifications to be tested with customer samples.

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*Nidec-Read Corporation to be renamed Nidec Advance Technology Corporation from April in 2023.

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More details...